



Final Product Change Notification

201405007F01

Issue Date: 11-Aug-2014
Effective Date: 22-Nov-2014

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QUALITY

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Change of bond wire and release of 2nd source mold compound in DFN2020MD-6 (SOT1220)

Details of this Change

Scheduled changes affect product types in DFN2020MD-6 (SOT1220) package only.

- (1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons.
- (2) The wire diameter of the gate wire will be changed from 23 μ m to 50 μ m.
- (3) A second source mold compound supplier will be introduced.

Old product: Wire material is Au (with currently used mold compound suppliers), gate wire diameter is 23 μ m.

Changed product: Wire material is Cu or Au (with currently used first and new second source mold compound supplier), gate wire diameter is 23 μ m (gold wire) or 50 μ m (copper wire).

The design and materials of all other components remain unchanged:

Die, die attach and lead frame.

Reliability qualification and full electrical characterization over temperature have been performed. For details please see the Self Qualification Report.

No change on thermal behavior or mechanical dimensions.

Electrical parameters will remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages.

Copper wire shows enhanced mechanical properties.

- (2) To streamline the production process, all wires in the package will get the same diameter.

- (3) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM for associated types in DFN2020MD-6 (SOT1220) package.

The second source supplier is already well established for NXP semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest samples request date for PCN samples is September 10, 2014.

Production

Planned first shipment 23-Nov-2014

Impact

No impact to the products' functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 10-Sep-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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